TM2308
N-CHANNEL ENHANCEMENT MOSFET

General Description

The TM2308 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

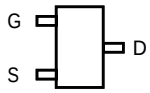
Product Summary

V_{DS}	60V
I_D (at V_{GS}=10V)	2.6A
$R_{DS(ON)}$ (at V_{GS}=10V)	< 100mΩ
$R_{DS(ON)}$ (at V_{GS} = 4.5V)	< 130mΩ

100% UIS Tested
100% R_g Tested

Green Product

SOT-23
Top View



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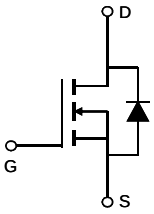


ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	60	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current (T_J = 150 °C)	T_C = 25 °C	I_D	2.6	A
	T_C = 70 °C		2.1	
	T_A = 25 °C		1.9[b, c]	
	T_A = 70 °C		1.5[b, c]	
Pulsed Drain Current		I_{DM}	8	
Continuous Source-Drain Diode Current	T_C = 25 °C	I_S	1.39	
	T_A = 25 °C		0.91[b, c]	
Avalanche Current	L = 0.1 mH	I_{AS}	6	
Single-Pulse Avalanche Energy		E_{AS}	1.8	mJ
Maximum Power Dissipation	T_C = 25 °C	P_D	1.66	W
	T_C = 70 °C		1.06	
	T_A = 25 °C		1.09[b, c]	
	T_A = 70 °C		0.7[b, c]	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

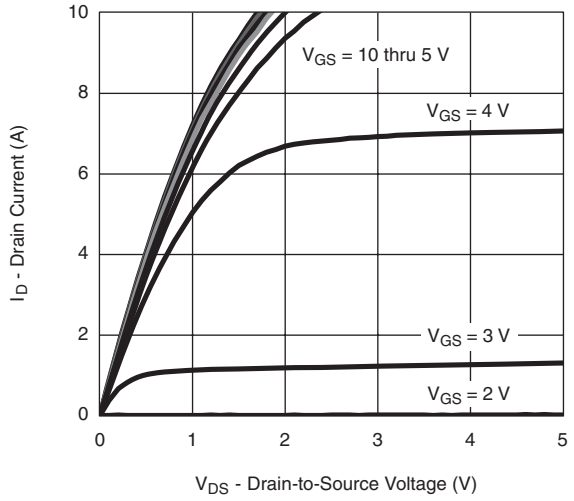
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient[b, d]	≤ 5 s	R_{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75	

Notes:
a. Based on T_C = 25 °C.
b. Surface Mounted on 1" x 1" FR4 board.
c. t = 5 s.
d. Maximum under Steady State conditions is 130 °C/W.

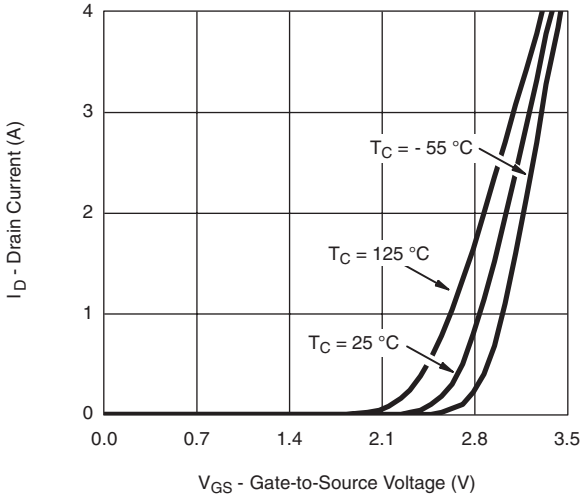
MOSFET SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
Parameter	**Symbol**	**Test Conditions**	**Min.**	**Typ.**	**Max.**	**Unit**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{DS} = 0 V, I_D = 250 µA	60			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	I_D = 250 µA		55		mV/°C
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			- 5		
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 µA	1		3	V
Gate-Source Leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 60 V, V_{GS} = 0 V			1	µA
		V_{DS} = 60 V, V_{GS} = 0 V, T_J = 55 °C			10	
On-State Drain Current[a]	$I_{D(on)}$	V_{DS} ≥ 5 V, V_{GS} = 10 V	8			A
Drain-Source On-State Resistance[a]	$R_{DS(on)}$	V_{GS} = 10 V, I_D = 2.6 A			100	mΩ
		V_{GS} = 4.5 V, I_D = 2.0 A			130	
Forward Transconductance[a]	g_{fs}	V_{DS} = 15V, I_D = 1.9 A		5		S
Dynamic[b]						
Input Capacitance	C_{iss}	V_{DS} = 30 V, V_{GS} = 0 V, f = 1 MHz		190		pF
Output Capacitance	C_{oss}			26		
Reverse Transfer Capacitance	C_{rss}			15		
Total Gate Charge	Q_g	V_{DS} = 30 V, V_{GS} = 10 V, I_D = 1.9 A		4.5	6.8	nC
		V_{DS} = 30 V, V_{GS} = 4.5 V, I_D = 1.9 A		2.3	3.5	
Gate-Source Charge	Q_{gs}			0.8		
Gate-Drain Charge	Q_{gd}			1		
Gate Resistance	R_g	f = 1 MHz	0.6	2.8	5.6	Ω
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 30 V, R_L = 20 Ω $I_D \cong$ 1.5 A, V_{GEN} = 10 V, R_G = 1 Ω		4	6	ns
Rise Time	t_r			10	15	
Turn-Off Delay Time	$t_{d(off)}$			10	15	
Fall Time	t_f			7	10.5	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 30 V, R_L = 20 Ω I_D = 1.5 A, V_{GEN} = 4.5 V, R_G = 1 Ω		15	23	ns
Rise Time	t_r			16	24	
Turn-Off Delay Time	$t_{d(off)}$			11	17	
Fall Time	t_f			11	17	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	T_C = 25 °C			1.39	A
Pulse Diode Forward Current[a]	I_{SM}				8	
Body Diode Voltage	V_{SD}	I_S = 1.5 A		0.8	1.2	V
Body Diode Reverse Recovery Time	t_{rr}	I_F = 1.5 A, di/dt = 100 A/µs, T_J = 25 °C		15	23	ns
Body Diode Reverse Recovery Charge	Q_{rr}			10	15	nC
Reverse Recovery Fall Time	t_a			12		ns
Reverse Recovery Rise Time	t_b			3		

Notes:
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.

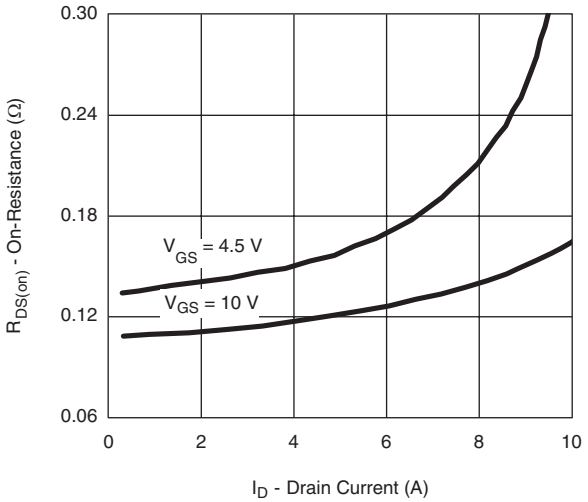
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



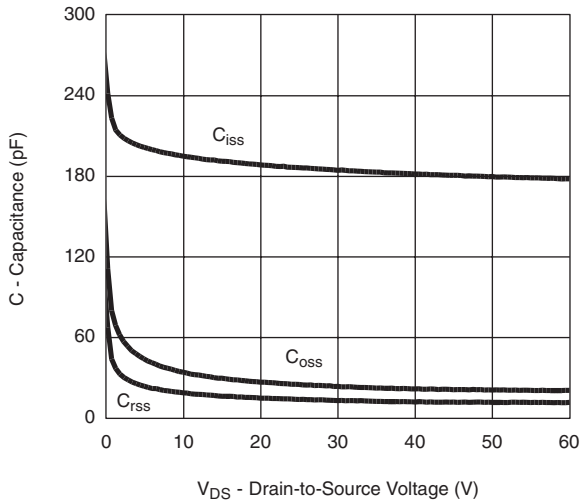
Output Characteristics



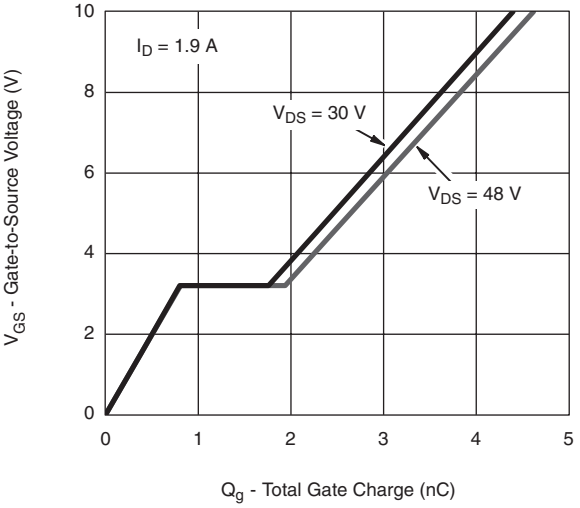
Transfer Characteristics



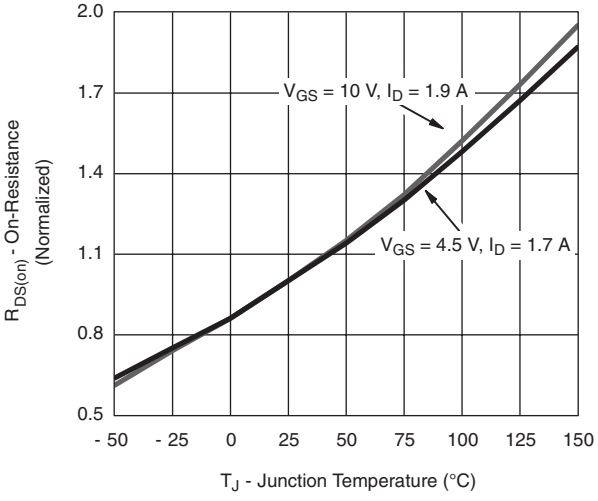
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

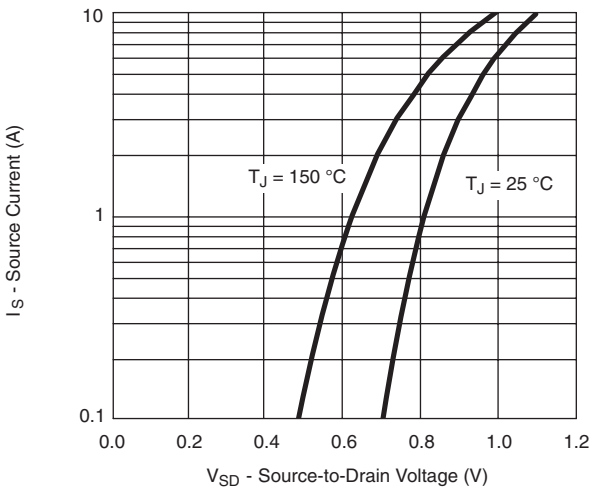


Gate Charge

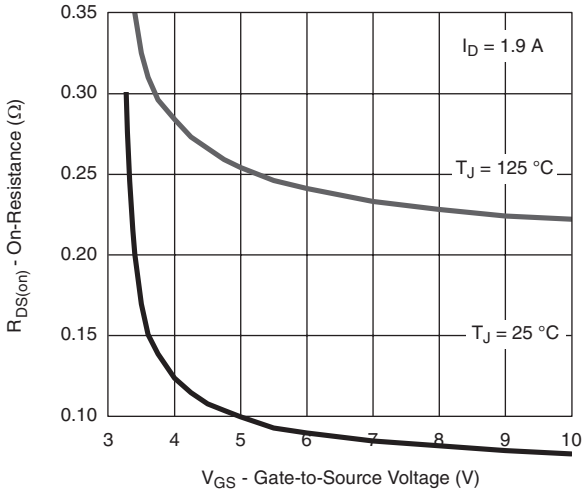


On-Resistance vs. Junction Temperature

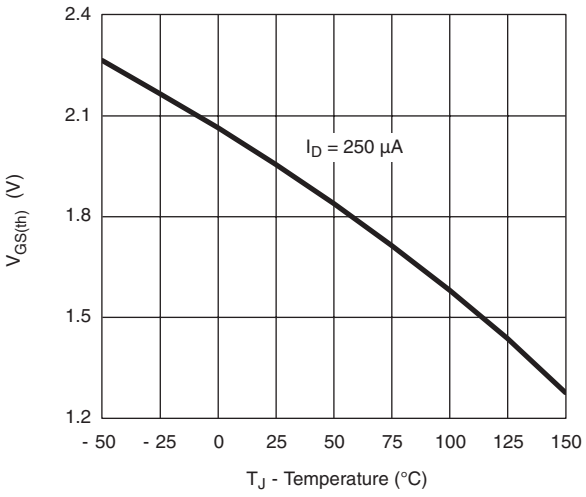
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



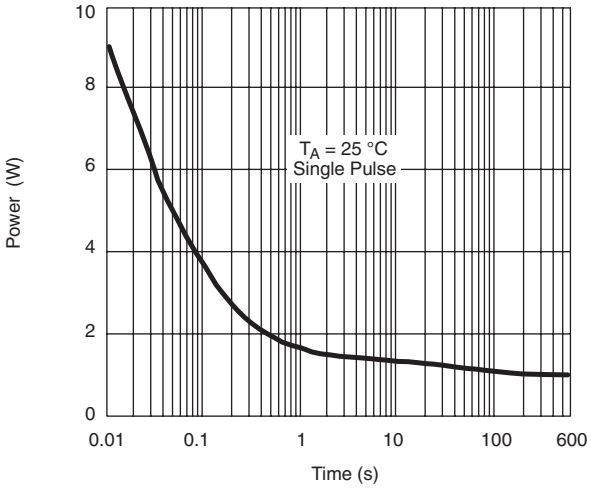
Source-Drain Diode Forward Voltage



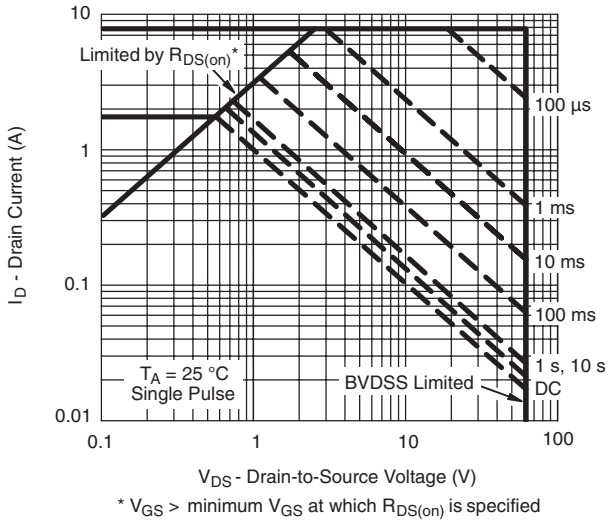
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



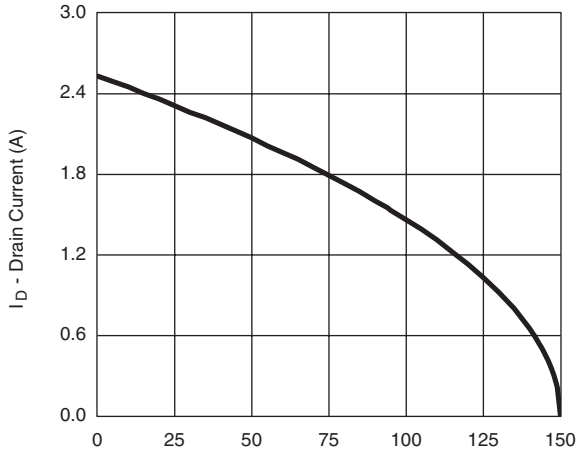
Single Pulse Power



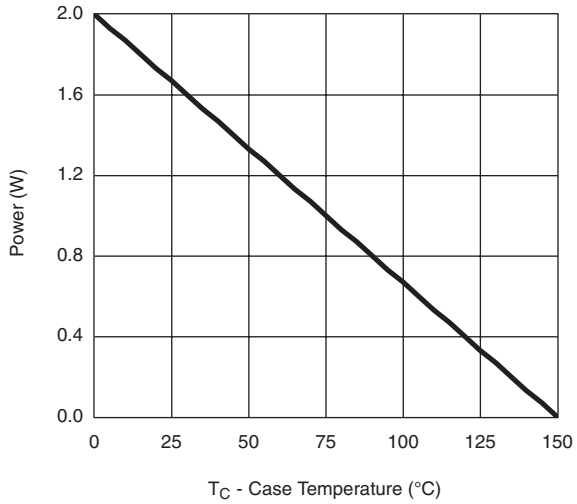
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

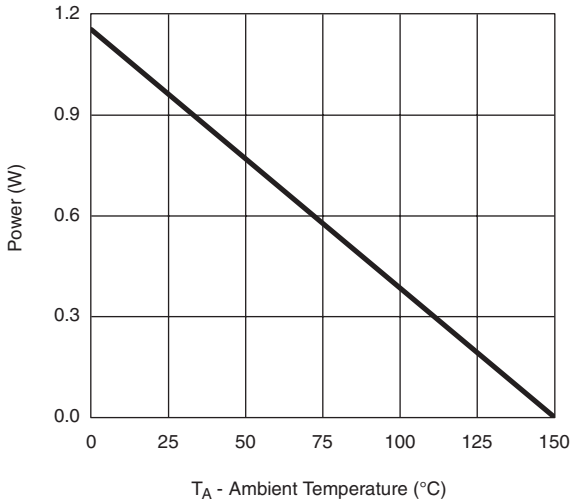
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*

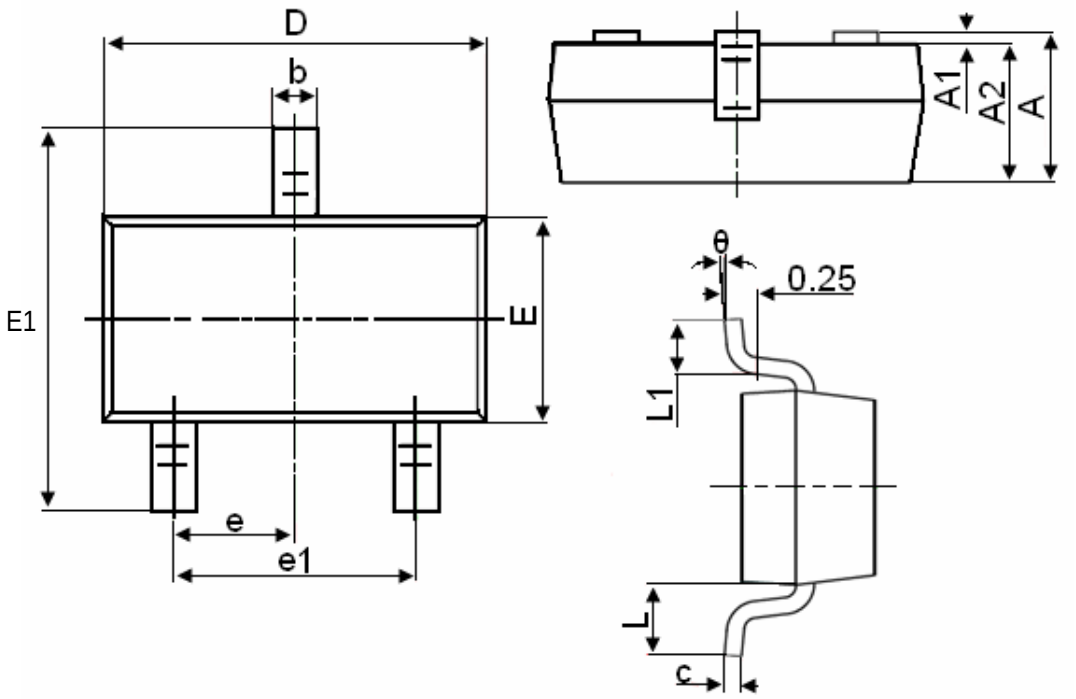


Power Derating, Junction-to-Case



Power Derating, Junction-to-Ambient

SOT-23 Package Information



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

Notes

1. All dimensions are in millimeters.
2. Tolerance ±0.10mm (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.